



32K x 16 Static RAM

Features

- 5.0V operation (± 10%)
- High speed
 - t_{AA} = 10 ns
- Low active power
 - 825 mW (max., 10 ns, "L" version)
- Very Low standby power
 550 μW (max., "L" version)
- · Automatic power-down when deselected
- Independent Control of Upper and Lower bytes
- Available in 44-pin TSOP II and 400-mil SOJ

Functional Description

The CY7C1020 is a high-performance CMOS static RAM organized as 32,768 words by 16 bits. This device has an automatic power-down feature that significantly reduces power consumption when deselected.

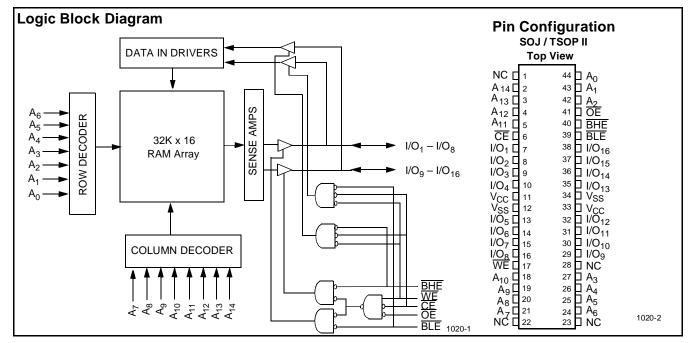
 $\frac{\text{Writing to the device is accomplished by taking Chip Enable}{(CE) and Write Enable (WE) inputs LOW. If Byte Low Enable}$

(\overline{BLE}) is LOW, then data from I/O pins (I/O₁ through I/O₈), is written into the location specified on the address pins (A₀ through A₁₄). If Byte High Enable (\overline{BHE}) is LOW, then data from I/O pins (I/O₉ through I/O₁₆) is written into the location specified on the address pins (A₀ through A₁₄).

Reading from the device is accomplished by taking Chip Enable ($\overline{\text{CE}}$) and Output Enable ($\overline{\text{OE}}$) LOW while forcing the Write Enable ($\overline{\text{WE}}$) HIGH. If Byte Low Enable ($\overline{\text{BLE}}$) is LOW, then data from the memory location specified by the address pins will appear on I/O₁ to I/O₈. If Byte High Enable ($\overline{\text{BHE}}$) is LOW, then data from memory will appear on I/O₉ to I/O₁₆. See the truth table at the back of this data sheet for a complete description of read and write modes.

The input/output pins (I/O₁ through I/O₁₆) are placed in a high-impedance state when the device is deselected (\overline{CE} HIGH), the outputs are disabled (\overline{OE} HIGH), the BHE and BLE are disabled (BHE, BLE HIGH), or during a write operation (\overline{CE} LOW, and \overline{WE} LOW).

The CY7C1020 is available in standard 44-pin TSOP type II and 400-mil-wide SOJ packages.



Selection Guide

| | | 7C1020-10 | 7C1020-12 | 7C1020-15 | 7C1020-20 |
|-----------------------------------|---|-----------|-----------|-----------|-----------|
| Maximum Access Time (ns) | | 10 | 12 | 15 | 20 |
| Maximum Operating Current (mA) | | 180 | 170 | 160 | 160 |
| | L | 150 | 140 | 130 | 130 |
| Maximum CMOS Standby Current (mA) | | 3 | 3 | 3 | 3 |
| | L | 0.1 | 0.1 | 0.1 | 0.1 |

Cypress Semiconductor Corporation



Maximum Ratings

| (Above which the useful life may be impaired. For user guide- lines, not tested.) |
|--|
| Storage Temperature65°C to +150°C |
| Ambient Temperature with Power Applied55°C to +125°C |
| Supply Voltage on V_{CC} to Relative $GND^{[1]}$ –0.5V to +7.0V |
| DC Voltage Applied to Outputs in High Z State ^[1] 0.5V to V_{CC} +0.5V DC Input Voltage ^[1] 0.5V to V_{CC} +0.5V |

Electrical Characteristics Over the Operating Range

| Current into Outputs (LOW) | 20 mA |
|---|-------|
| Static Discharge Voltage> (per MIL-STD-883, Method 3015) | 2001V |
| Latak Lia Oromani | ~ ^ |

Latch-Up Current......>200 mA

Operating Range

| Range | Ambient Temperature ^[2] | v _{cc} |
|------------|---------------------------------------|-----------------|
| Commercial | 0°C to +70°C | 4.5V–5.5V |

| | | Test Conditions | | 7C10 | 20-10 | 7C1020-12 | | 7C1020-15 | | |
|------------------|------------------------------------|---|----|------|-------|-----------|------|-----------|------|------|
| Parameter | Description | | | Min. | Max. | Min. | Max. | Min. | Max. | Unit |
| V _{OH} | Output HIGH Voltage | V_{CC} = Min., I_{OH} = -4.0 | mA | 2.4 | | 2.4 | | 2.4 | | V |
| V _{OL} | Output LOW Voltage | V _{CC} = Min., I _{OL} = 8.0 m | A | | 0.4 | | 0.4 | | 0.4 | V |
| V _{IH} | Input HIGH Voltage | | | 2.2 | 6.0 | 2.2 | 6.0 | 2.2 | 6.0 | V |
| V _{IL} | Input LOW Voltage ^[1] | | | -0.5 | 0.8 | -0.5 | 0.8 | -0.5 | 0.8 | V |
| I _{IX} | Input Load Current | $GND \leq V_I \leq V_{CC}$ | | -1 | +1 | -1 | +1 | -1 | +1 | μA |
| I _{OZ} | Output Leakage Current | $GND \le V_I \le V_{CC},$ Output Disabled | | -2 | +2 | -2 | +2 | -2 | +2 | μA |
| I _{CC} | V _{CC} Operating | V _{CC} = Max., | | | 180 | | 170 | | 160 | mA |
| | Supply Current | $I_{OUT} = 0 \text{ mA},$ f = f _{MAX} = 1/t _{RC} | L | | 150 | | 140 | | 130 | |
| I _{SB1} | Automatic CE | Max. V _{CC} , <u>CE</u> ≥ V _{IH} | | | 20 | | 20 | | 20 | mA |
| | Power-Down Current —TTL Inputs | $V_{IN} \ge V_{IH} \text{ or}$ $V_{IN} \le V_{IL}, f = f_{MAX}$ | L | | 10 | | 10 | | 10 | |
| I _{SB2} | Automatic CE | Max. V _{CC} , | | | 3 | | 3 | | 3 | mA |
| | Power-Down Current —CMOS Inputs | $\label{eq:constraint} \begin{array}{l} \overline{\text{CE}} \geq V_{\text{CC}} - 0.3\text{V}, \\ V_{\text{IN}} \geq V_{\text{CC}} - 0.3\text{V}, \\ \text{or } V_{\text{IN}} \leq 0.3\text{V}, \text{f} = 0 \end{array}$ | L | | 100 | | 100 | | 100 | μA |

Notes:

1. V_{IL} (min.) = -2.0V for pulse durations of less than 20 ns. 2. T_A is the case temperature.



Electrical Characteristics Over the Operating Range (continued)

| | | | | 7C10 | 20-20 | |
|------------------|------------------------------------|--|--------|------|-------|------|
| Parameter | Description | Test Conditions | 6 | Min. | Max. | Unit |
| V _{OH} | Output HIGH Voltage | V _{CC} = Min., I _{OH} = -4.0 mA | | 2.4 | | V |
| V _{OL} | Output LOW Voltage | V _{CC} = Min., I _{OL} = 8.0 mA | | | 0.4 | V |
| V _{IH} | Input HIGH Voltage | | | 2.2 | 6.0 | V |
| V _{IL} | Input LOW Voltage ^[1] | | | -0.5 | 0.8 | V |
| I _{IX} | Input Load Current | $GND \le V_I \le V_{CC}$ | | -1 | +1 | μΑ |
| I _{OZ} | Output Leakage Current | GND ≤ V _I ≤ V _{CC} , Output Di | sabled | -2 | +2 | μΑ |
| I _{CC} | V _{CC} Operating | V _{CC} = Max., | | | 160 | mA |
| | Supply Current | $I_{OUT} = 0 \text{ mA},$ f = f _{MAX} = 1/t _{RC} | L | | 130 | |
| I _{SB1} | Automatic CE | Max. V _{CC} , <u>CE</u> ≥ V _{IH} | | | 20 | mA |
| | Power-Down Current — TTL Inputs | $V_{IN} \ge V_{IH} \text{ or}$ $V_{IN} \le V_{IL}, f = f_{MAX}$ | L | | 10 | |
| I _{SB2} | Automatic CE | Max. V _{CC} , | | | 3 | mA |
| | Power-Down Current —CMOS Inputs | $\label{eq:central_cond} \begin{split} \overline{CE} &\geq V_{CC} - 0.3V, \\ V_{IN} &\geq V_{CC} - 0.3V, \\ \text{or } V_{IN} &\leq 0.3V, \ f = 0 \end{split}$ | L | | 100 | μA |

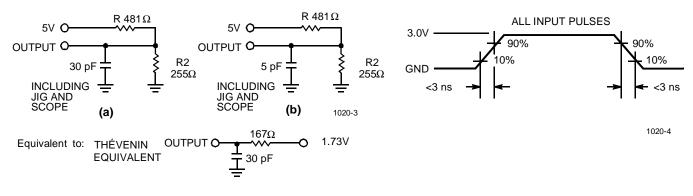
Capacitance^[3]

| Parameter | Description | Test Conditions | Max. | Unit |
|------------------|--------------------|---|------|------|
| C _{IN} | Input Capacitance | $T_A = 25^{\circ}C, f = 1 \text{ MHz},$ | 8 | pF |
| C _{OUT} | Output Capacitance | $V_{CC} = 5.0V$ | 8 | pF |

Note:

3. Tested initially and after any design or process changes that may affect these parameters.

AC Test Loads and Waveforms





Switching Characteristics^[4] Over the Operating Range

| | | 7C10 | 20-10 | 7C1020-12 | | 7C1020-15 | | 7C1020-20 | | |
|-------------------|-------------------------------------|------|-------|-----------|------|-----------|------|-----------|------|------|
| Parameter | Description | Min. | Max. | Min. | Max. | Min. | Max. | Min. | Max. | Unit |
| READ CYC | ĹĒ | • | | | | | | | | |
| t _{RC} | Read Cycle Time | 10 | | 12 | | 15 | | 20 | | ns |
| t _{AA} | Address to Data Valid | | 10 | | 12 | | 15 | | 20 | ns |
| t _{OHA} | Data Hold from Address Change | 3 | | 3 | | 3 | | 3 | | ns |
| t _{ACE} | CE LOW to Data Valid | | 10 | | 12 | | 15 | | 20 | ns |
| t _{DOE} | OE LOW to Data Valid | | 5 | | 5 | | 7 | | 9 | ns |
| t _{LZOE} | OE LOW to Low Z | 0 | | 0 | | 0 | | 0 | | ns |
| t _{HZOE} | OE HIGH to High Z ^[5, 6] | | 5 | | 6 | | 7 | | 8 | ns |
| t _{LZCE} | CE LOW to Low Z ^[6] | 3 | | 3 | | 3 | | 3 | | ns |
| t _{HZCE} | CE HIGH to High Z ^[5, 6] | | 5 | | 6 | | 7 | | 8 | ns |
| t _{PU} | CE LOW to Power-Up | 0 | | 0 | | 0 | | 0 | | ns |
| t _{PD} | CE HIGH to Power-Down | | 12 | | 12 | | 15 | | 20 | ns |
| t _{DBE} | Byte enable to Data Valid | | 5 | | 6 | | 7 | | 9 | ns |
| t _{LZBE} | Byte enable to Low Z | 0 | | 0 | | 0 | | 0 | | ns |
| t _{HZBE} | Byte disable to High Z | | 5 | | 6 | | 7 | | 9 | ns |
| WRITE CYC | LE ^[7] | • | | • | • | | • | | • | |
| t _{WC} | Write Cycle Time | 10 | | 12 | | 15 | | 12 | | ns |
| t _{SCE} | CE LOW to Write End | 8 | | 9 | | 10 | | 12 | | ns |
| t _{AW} | Address Set-Up to Write End | 7 | | 8 | | 10 | | 12 | | ns |
| t _{HA} | Address Hold from Write End | 0 | | 0 | | 0 | | 0 | | ns |
| t _{SA} | Address Set-Up to Write Start | 0 | | 0 | | 0 | | 0 | | ns |
| t _{PWE} | WE Pulse Width | 7 | | 8 | | 10 | | 12 | | ns |
| t _{SD} | Data Set-Up to Write End | 5 | | 6 | | 10 | | 10 | | ns |
| t _{HD} | Data Hold from Write End | 0 | | 0 | | 0 | | 0 | | ns |
| t _{LZWE} | WE HIGH to Low Z ^[6] | 3 | | 3 | | 3 | | 3 | | ns |
| t _{HZWE} | WE LOW to High Z ^[5, 6] | | 5 | | 6 | | 7 | | 9 | ns |
| t _{BW} | Byte enable to end of write | 7 | | 8 | | 9 | | 12 | | ns |

Notes:

Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified 4. I_{OL}/I_{OH} and 30-pF load capacitance.

5.

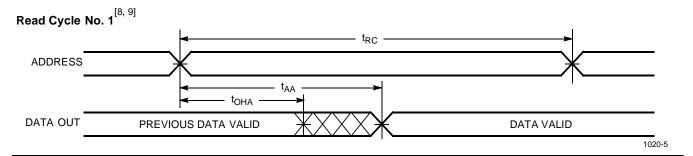
6.

To(JOH and 3O+P load capacitation). t_{HZOE}, t_{HZDE}, t_{HZZE}, and t_{HZWE} are specified with a load capacitance of 5 pF as in part (b) of AC Test Loads. Transition is measured ±500 mV from steady-state voltage. At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE}, t_{HZDE} is less than t_{LZCE}, and t_{HZWE} is less than t_{LZWE} for any given device. The internal write time of the memory is defined by the overlap of CE LOW, WE LOW and BHE / BLE LOW. CE, WE and BHE / BLE must be LOW to initiate a write, and the transition of these signals can terminate the write. The input data set-up and hold timing should be referenced to the leading edge of the signal that terminates the write. 7.

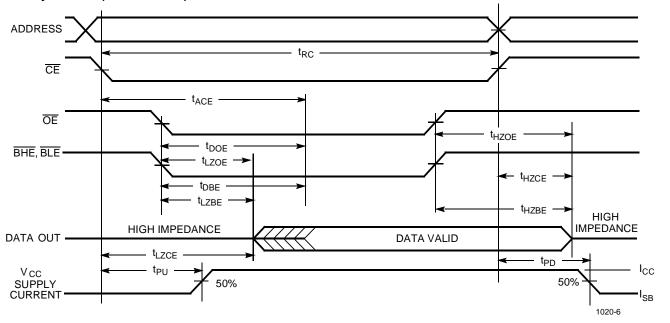


CY7C1020

Switching Waveforms



Read Cycle No. 2 ($\overline{\text{OE}}$ Controlled) ^[9, 10]



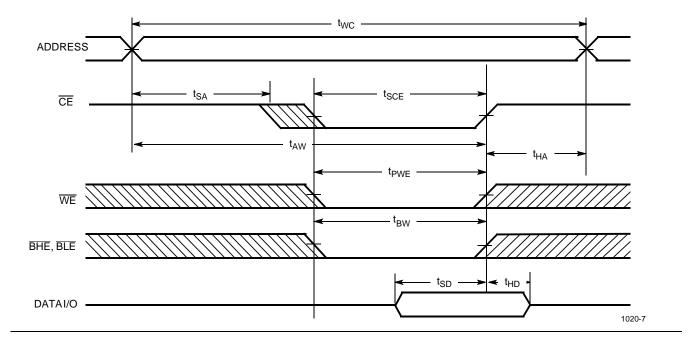
Notes:

8. Device is continuously selected. \overline{OE} , \overline{CE} , \overline{BHE} and/or $\overline{BHE} = V_{\parallel}$. 9. \overline{WE} is HIGH for read cycle. 10. Address valid prior to or coincident with \overline{CE} transition LOW.

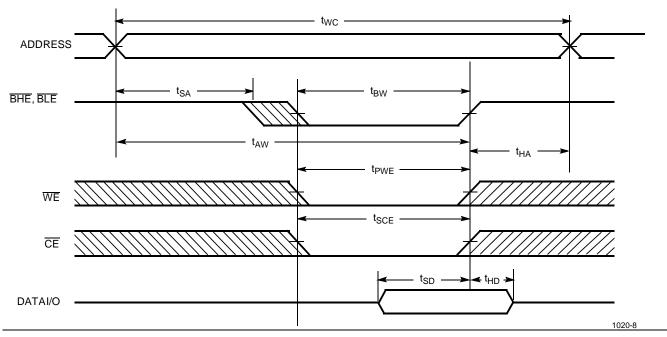


Switching Waveforms (continued)

Write Cycle No. 1 ($\overline{\text{CE}}$ Controlled)^[11, 12]



Write Cycle No. 2 (BLE or BHE Controlled)



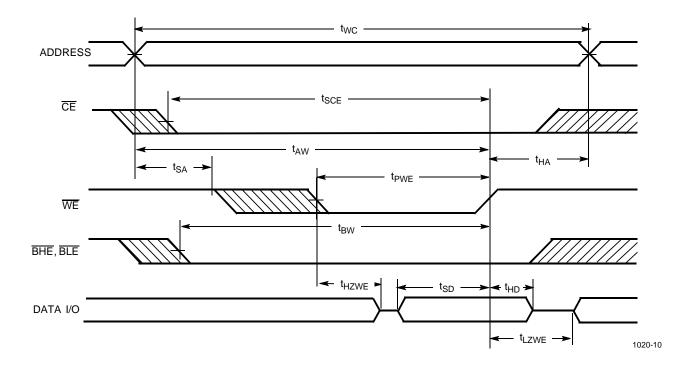
Notes:

Data I/O is high impedance if OE or BHE and/or BLE = V_{IH}.
If CE goes HIGH simultaneously with WE going HIGH, the output remains in a high-impedance state.



Switching Waveforms (continued)

Write Cycle No.3 (WE Controlled, OE LOW)



Truth Table

| CE | OE | WE | BLE | BHE | 1/0 ₁ –1/0 ₈ | I/O ₉ –I/O ₁₆ | Mode | Power |
|----|----|----|-----|-----|------------------------------------|-------------------------------------|----------------------------|----------------------------|
| Н | Х | Х | Х | Х | High Z | High Z | Power-Down | Standby (I _{SB}) |
| L | L | Н | L | L | Data Out | Data Out | Read - All bits | Active (I _{CC}) |
| | | | L | Н | Data Out | High Z | Read - Lower bits only | Active (I _{CC}) |
| | | | Н | L | High Z | Data Out | Read - Upper bits only | Active (I _{CC}) |
| L | Х | L | L | L | Data In | Data In | Write - All bits | Active (I _{CC}) |
| | | | L | Н | Data In | High Z | Write - Lower bits only | Active (I _{CC}) |
| | | | Н | L | High Z | Data In | Write - Upper bits only | Active (I _{CC}) |
| L | Н | Н | Х | Х | High Z | High Z | Selected, Outputs Disabled | Active (I _{CC}) |
| L | Х | Х | Н | Н | High Z | High Z | Selected, Outputs Disabled | Active (I _{CC}) |



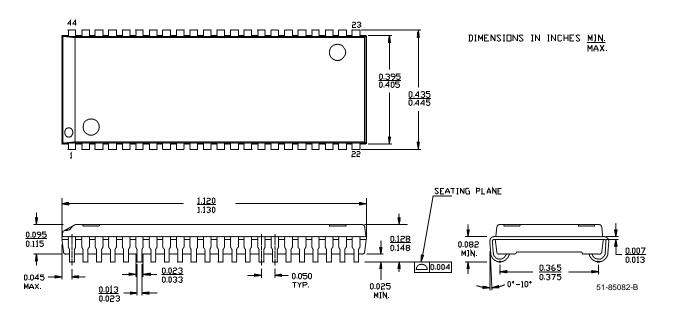
Ordering Information

| Speed (ns) | Ordering Code | Package Name | Package Type | Operating Range |
|---------------|----------------|-----------------|------------------------------|--------------------|
| 10 | CY7C1020-10VC | V34 | 44-Lead (400-Mil) Molded SOJ | Commercial |
| | CY7C1020L-10VC | V34 | 44-Lead (400-Mil) Molded SOJ | Commercial |
| | CY7C1020-10ZC | Z44 | 44-Lead TSOP Type II | Commercial |
| | CY7C1020L-10ZC | Z44 | 44-Lead TSOP Type II | Commercial |
| 12 | CY7C1020-12VC | V34 | 44-Lead (400-Mil) Molded SOJ | Commercial |
| | CY7C1020L-12VC | V34 | 44-Lead (400-Mil) Molded SOJ | Commercial |
| | CY7C1020-12ZC | Z44 | 44-Lead TSOP Type II | Commercial |
| | CY7C1020L-12ZC | Z44 | 44-Lead TSOP Type II | Commercial |
| 15 | CY7C1020-15VC | V34 | 44-Lead (400-Mil) Molded SOJ | Commercial |
| | CY7C1020L-15VC | V34 | 44-Lead (400-Mil) Molded SOJ | Commercial |
| | CY7C1020-15ZC | Z44 | 44-Lead TSOP Type II | Commercial |
| | CY7C1020L-15ZC | Z44 | 44-Lead TSOP Type II | Commercial |
| 20 | CY7C1020-20VC | V34 | 44-Lead (400-Mil) Molded SOJ | Commercial |
| | CY7C1020L-20VC | V34 | 44-Lead (400-Mil) Molded SOJ | Commercial |
| | CY7C1020-20ZC | Z44 | 44-Lead TSOP Type II | Commercial |
| | CY7C1020L-20ZC | Z44 | 44-Lead TSOP Type II | Commercial |

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Package Diagrams

44-Lead (400-Mil) Molded SOJ V34

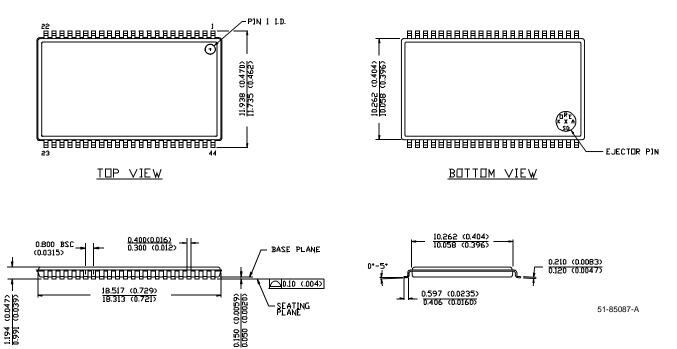




Package Diagrams (continued)

44-Pin TSOP II Z44

DIMENSION IN MM (INCH)



51-85087-A

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